

ABSTRACT OF THE DISCLOSURE

5 An electrode assembly of a semiconductor processing chamber wherein heat
transfer between a backing plate and a showerhead electrode is improved by an
electrostatic clamping arrangement, which includes a compliant material in contact
with a surface of the showerhead electrode. The showerhead electrode is
removably attached to the backing plate by a mechanical clamping arrangement
which engages an outer periphery of the showerhead electrode. The electrostatic
clamping arrangement is coextensive with the showerhead electrode to improve
thermal conduction between the backing plate and the showerhead electrode.

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